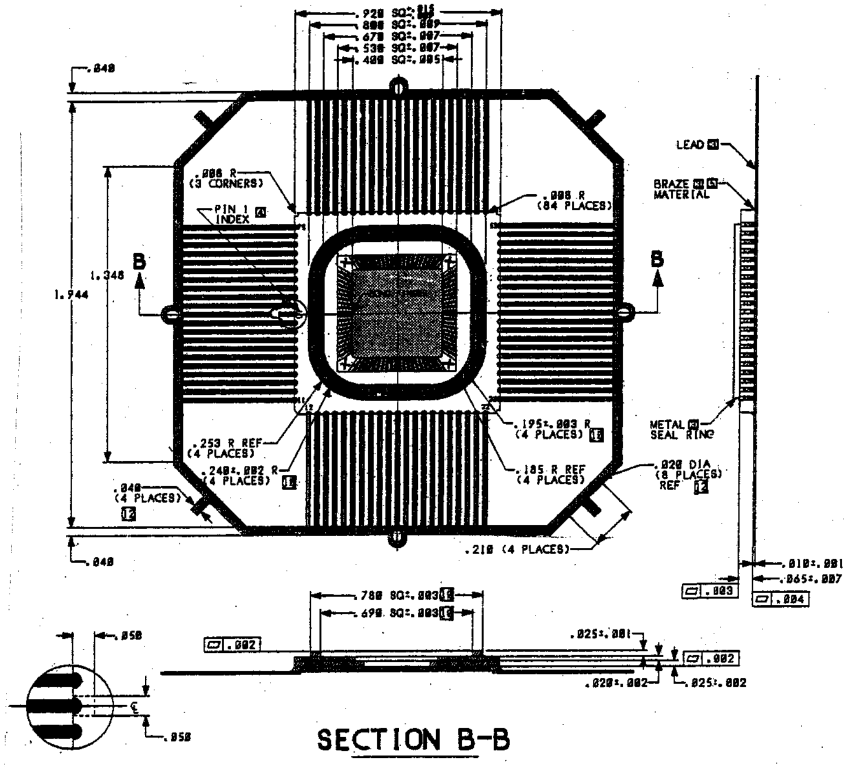
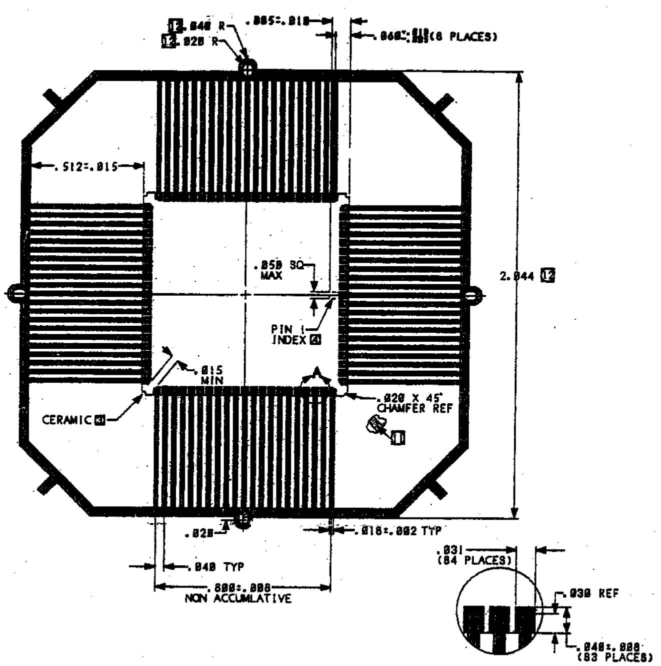
# SSM P/N CCF08414



SECTION B-B

DETAIL C



DETAIL A

| | | |
|---|---|---|
| | | |
| | | |
| KYOCERA INTERNATIONAL INC. SENDAI PLANT<br>1810 TAKI-CHO SENDAI-SHI KAGOSHIMA 89-02 JAPAN | | PB-F90603 |
| NAME AND ADDRESS | CAGE NO. | PART NO. |
| APPROVED SOURCES OF SUPPLY | | |

SOURCE CONTROL DRAWING

13. BOND FINGER PATTERN CENTERLINE IS ALIGNED TO DIE CAVITY CENTERLINE ±.004
12. THIS FEATURE IS VENDORS OPTION.
11. EDGE METALLIZED.
10. THIS DIMENSION IS FOR THE METAL SEAL RING.
9. LEAD RESISTANCE SHALL BE 0.500 OHMS MAX.
8. WHEN TESTED IN ACCORDANCE WITH MIL STD 883, TEST METHOD 2001, IN THE Y-1 DIRECTION, THE PACKAGE SHALL BE CAPABLE OF WITHSTANDING 30K G'S CONSTANT ACCELERATION.
7. SEAL RING AND DIE ATTACH PAD SHALL BE ELECTRICALLY ISOLATED FROM ANY LEADS.
6. DIE ATTACH PAD SHALL BE METALLIZED.
5. BRAZE FILLETS SHALL BE CONCAVE.
4. PIN 1 INDEX MARK CONFIGURATION SHALL BE VENDORS OPTION, AND SHALL BE LOCATED ADJACENT TO PIN 1 AND WITHIN THE AREA DEFINED BY DASHED LINES. PIN 1 INDEX METALLIZATION MAY BE PLATED WITH NICKEL AND OR GOLD, BUT NOT REQUIRED TO MEET NOTE 2.
3. MATERIALS:
   3.1 LEADS SHALL BE TYPE A OR B PER PARAGRAPH 3.3.3.3 OF PS 79032 (KOVAR OR ALLOY 42)
   3.2 BRAZE MATERIAL SHALL BE AG-CU PER PARAGRAPH 3.3.3.5.A OR B OF PS 79032
   3.3 CERAMIC SHALL BE OPAQUE (DARK BROWN OR BLACK) 90% MINIMUM ALUMINA PER PARAGRAPH 3.3.3.1 OF PS 79032.
   3.4 CERAMIC METALLIZATION SHALL BE NOMINALLY PURE TUNGSTEN PER PARAGRAPH 3.3.3.2 OF PS 79032. (LIGHTLY SHADED AREAS).
   3.5 METAL SEAL RING SHALL BE TYPE A (KOVAR) PER PARAGRAPH 3.3.3.4 OF PS 79032.
2. ALL EXPOSED METALLIZED AND METAL SURFACES SHALL BE PLATED WITH 100-225 MICRO-INCHES OF GOLD OVER 80-350 OF NICKEL IN ACCORDANCE WITH MIL-M-38510, MIL-G-45204, TYPE III, GRADE A AND QQ-N-290. THE 80 MICROINCHES OF NICKEL INCLUDES COVERAGE OVER ALL EXPOSED BRAZING MATERIAL. THE FINISH SHALL BE COMPATABLE WITH INDUSTRY STANDARD EUTECTIC AND SILVER FILLED GLASS DIE ATTACH MATERIALS AND PROCESSES.
1. THIS PACKAGE SHALL MEET ALL OF THE APPLICABLE REQUIREMENTS OF PS 79032, GENERAL SPECIFICATION FOR COFIRED CERAMIC PACKAGES. ALL REQUIREMENTS OF PS 79032 NOT DEFINED FOR A SPECIFIC PACKAGE CONFIGURATION OR PACKAGE ELEMENT SHALL APPLY FOR ALL CONFIGURATIONS.

NOTES: UNLESS OTHERWISE SPECIFIED.

| RELEASE PRINT | | |
|---|---|---|
| — | 91/02-01 | |
| REV. | REL. DATE | REL. BY |

| QTY REQD | CAGE CODE | PART OR IDENTIFYING NO. | NOMENCLATURE OR DESCRIPTION | ZONE | ITEM NO |
|---|---|---|---|---|---|

PARTS LIST

NEXT ASSY | USED ON
APPLICATION

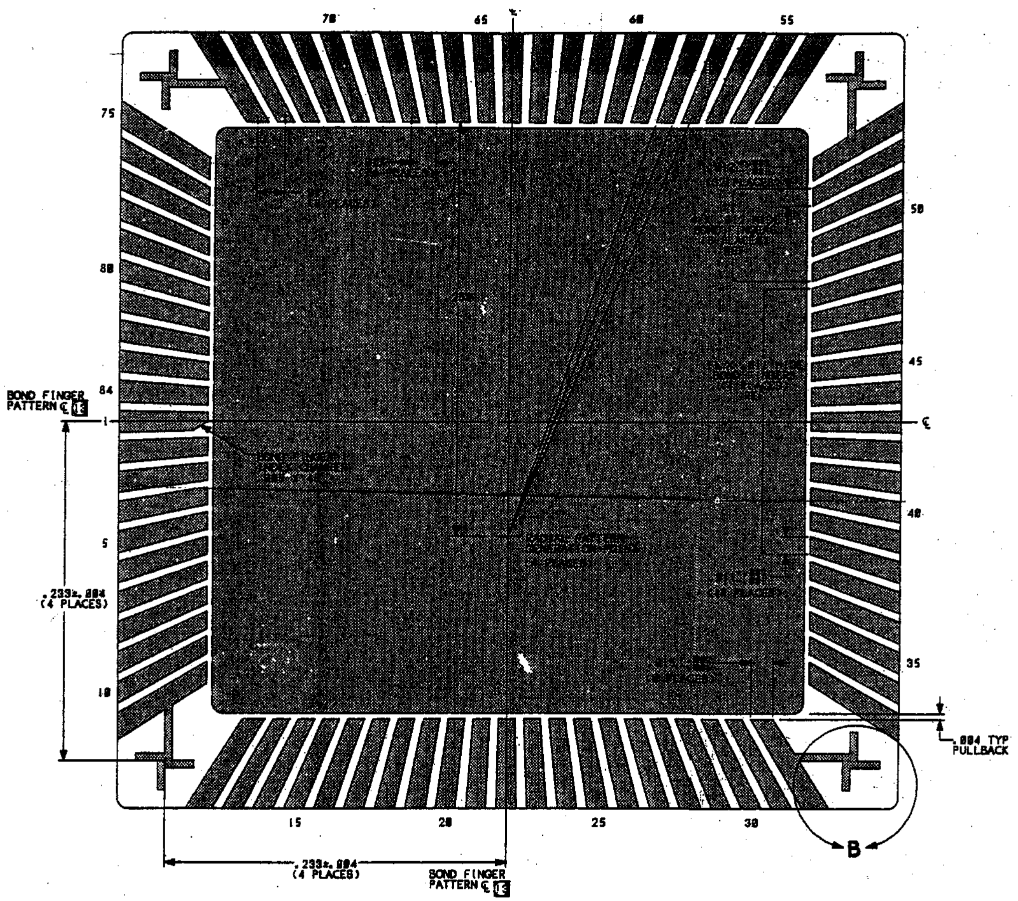
EXCEPT AS NOTED DIM ARE IN INCHES PER ANSI Y14.5
.XXX ±.005 .XX ±.03 ANGLES ±.5°
MATERIAL

CONTRACT:
DWN 90/12/18
CHK 10 JAN 91
91/01/30
APVD 91/01/29

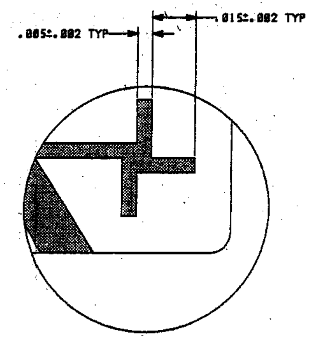
PACKAGE, 84 LEAD LEADED CHIP CARRIER, .040 CENTERS, .400 SQ. CAVITY

SIZE C | CAGE CODE 62458 | DWG NO 6133028
SCALE 3/1 | SHEET 1 OF 2

# SSM P/N CCF08414



BOND FINGER CONFIGURATION



DETAIL B

| | CONTRACT: | | |
|---|---|---|---|
| DWN S.L. Egan 90/12/10 | SIZE<br>C | CAGE CODE<br>62458 | DWG NO<br>6133028 |
| | SCALE 20/1 | | SHEET 2 OF 2 |